

Features

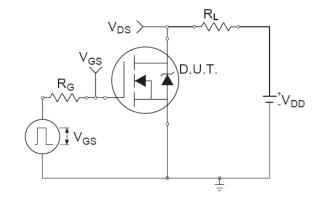
- V_{DSS} =40V/ V_{GSS} =±20V/ I_D =130A $R_{DS(ON)}$ =4m Ω (max.)@ V_{GS} =10V
- High Dense Cell Design
- Reliable and Rugged
- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance

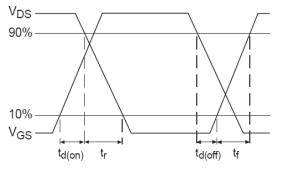
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Applications

- Power Management in Inverter System
- Synchronous Rectification "

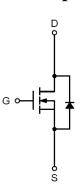
Switching Time Test Circuit and Waveforms





""" Pin Description

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Marking and pin Assignment



TO-220-3L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM1404B	HM1404B	TO-220-3L	-	-	-

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Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit
$ m V_{DSS}$	Drain-Source Voltage	40	V
$V_{ m GSS}$	Gate –Source Voltage	±20	V
т	T _C =100°C	100	A
I_D	Continuous Drain Current	130	A
I_{DP}	300us Pulsed Drain Current Tested T _C =25°C	300	A
I_{S}	Diode Continuous Forward Current	30	A
$T_{\rm J}$	Operating Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 ~ 150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

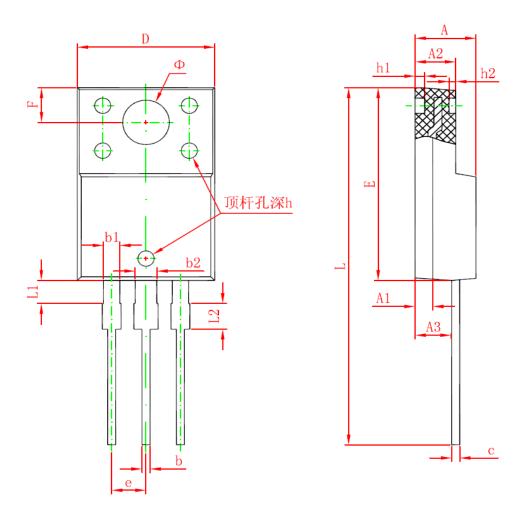
Symbol	Parameter	Parameter Test Conditions		Тур	Max.	Unit	
Static Char	acteristics						
$\mathrm{BV}_{\mathrm{DSS}}$	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250uA	40			V	
$I_{ m DSS}$	Zero Gate Voltage Drain Current	V _{DS} =32V,V _{GS} =0V T _J =85°C			100	uA	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=250uA$	1	2	3	V	
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA	
$R_{DS(on)}^{1}$	Drain-Source On-Resistance	$V_{GS}=10V, I_{D}=30A$		3.2	4	mΩ	
Diode Chai	racteristics						
${ m V_{SD}}^1$	Diode Forward Voltage	$I_{SD} = 30A, V_{GS} = 0V$		0.85	1.3	V	
t _{rr}	Reverse Recovery Time	I_{SD} =30A,		50		ns	
Q_{rr}	Reverse Recovery Charge	$dI_{SD}/dt=100A/us$		90		nC	
Dynamic C	haracteristics ²						
R_G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Frequency=1MHz		1.5		Ω	
C _{iss}	Input Capacitance			4500		pF	
Coss	Output Capacitance	$V_{GS}=0V$, $V_{DS}=20V$		800			
C_{rss}	Reverse Transfer Capacitance	Frequency=1MHz		240			
$t_{d(on)}$	Turn-On Delay Time	V -20V P -20O		19			
$t_{\rm r}$	Turn-On Rise Time	V_{DD} =20V, R_L =30 Ω I_D =1.0A, V_{GEN} =10V		14		ns	
$t_{d(off)}$	Turn-Off Delay Time	$R_G=6\Omega$		60			
t_{f}	Turn-Off Fall Time	NG-022		35			
Gate Charg	ge Characteristics ²						
Q_{g}	Total Gate Charge	V -20V V -10V		85		nC	
Q_{gs}	Gate-Source Charge	$V_{DS}=20V, V_{GS}=10V$		30			
Q_{gd}	Gate-Drain Charge	$I_D=30A$		23			

Note:

- 1: Pulse test; pulse width \leq 300ns, duty cycle \leq 2%.
- 2: Guaranteed by design, not subject to production testing.



TO-220F PACKAGE OUTLINE DIMENSIONS



C: mah al	Dimensions In Millimeters		Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
Α	4.300	4.700	0.169	0.185		
A1	1.300 REF.		0.051 REF.			
A2	2.800	3.200	0.110	0.126		
A3	2.500	2.900	0.098	0.114		
b	0.500	0.750	0.020	0.030		
b1	1.100	1.350	0.043	0.053		
b2	1.500	1.750	0.059	0.069		
С	0.500	0.750	0.020	0.030		
D	9.960	10.360	0.392	0.408		
Е	14.800	15.200	0.583	0.598		
е	2.540	TYP.	0.100	TYP.		
F	2.700 REF.		0.106 REF.			
Ф	3.500	3.500 REF.		0.138 REF.		
h	0.000	0.300	0.000	0.012		
h1	0.800 REF.		0.031 REF.			
h2	0.500 REF.		0.020 REF.			
L	28.000	28.400	1.102	1.118		
L1	1.700	1.900	0.067	0.075		
L2	1.900	2.100	0.075	0.083		





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